**Vishay Semiconductors** 

# **INT-A-PAK Power Modules Ultrafast Diodes, 300 A**

INT-A-PAK

PRODUCT SUMMARY				
I <sub>F(AV)</sub> at T <sub>C</sub>	300 A at 48 °C			
V <sub>R</sub>	600 V			
t <sub>rr</sub> (typical)	130 ns			
I <sub>F(DC)</sub> at T <sub>C</sub>	230 A at 100 °C			

### **FEATURES**

- Electrically insulated by DBC ceramic
- 3500 V<sub>RMS</sub> isolating voltage
- Standard JEDEC package
- Simplified mechanical designs, rapid assembly
- High surge capability
- Large creepage distances
- UL approved file E78996
- Case style INT-A-PAK
- Compliant to RoHS directive 2002/95/EC
- Designed and gualified for industrial level

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Cathode to anode voltage	V <sub>R</sub>		600	V		
		$T_{\rm C} = 25 \ ^{\circ}{\rm C}$	435			
Continuous forward current per leg	١ <sub>F</sub>	T <sub>C</sub> = 100 °C	230	А		
Single pulse forward current	I <sub>FSM</sub>	Limited by junction temperature	TBD			
Maximum power dissipation per leg	р	$T_{\rm C} = 25 \ ^{\circ}{\rm C}$	781	w		
Maximum power dissipation per leg	PD	T <sub>C</sub> = 100 °C	313	vv		
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		- 40 to 150	°C		
RMS insulation voltage	V <sub>INS</sub>	s 50 Hz, circuit to base, all terminals shorted, t = 1 s 3500		V		

<b>ELECTRICAL SPECIFICATIONS</b> ( $T_J = 25 \text{ °C}$ unless otherwise specified)							
PARAMETER	SYMBOL	MBOL TEST CONDITIONS MIN. TYP. M		MAX.	UNITS		
Cathode to anode breakdown voltage	V <sub>BR</sub>	I <sub>R</sub> = 500 μA	600	-	-		
		I <sub>F</sub> = 150 A	-	1.23	1.53		
Forward valtage drep per leg	V	I <sub>F</sub> = 300 A	-	1.43	1.96	V	
Forward voltage drop per leg	V <sub>FM</sub>	I <sub>F</sub> = 150 A, T <sub>J</sub> = 125 °C	-	1.11	1.29		
		I <sub>F</sub> = 300 A, T <sub>J</sub> = 125 °C	-	1.39	1.73		
Maximum reverse leakage current	I <sub>RM</sub>	$T_{\rm J} = 150 \ ^{\circ}\text{C}, \ V_{\rm R} = 600 \ \text{V}$	-	-	50	mA	



RoHS

COMPLIANT



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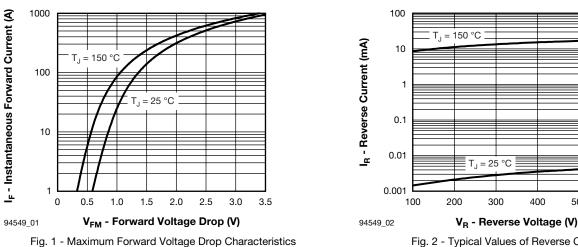
<b>DYNAMIC RECOVERY CHARACTERISTICS</b> ( $T_J = 25$ °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS	
Reverse recovery time	+	T <sub>J</sub> = 25 °C		-	130	165	A nC	
neverse recovery lime	t <sub>rr</sub>	T <sub>J</sub> = 125 °C		-	195	260		
Peak recovery current	I	$T_{\rm J} = 25 ^{\circ}{\rm C}$ $I_{\rm F} = 50 {\rm A}$	I <sub>F</sub> = 50 A	-	11	18		
Feak recovery current	l <sub>rr</sub>	T <sub>J</sub> = 125 °C	dl/dt = 200 A/µs	-	20	30		
Reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C	V <sub>R</sub> = 400 V (per leg)	-	670	1485		
neverse recovery charge	Qrr	T <sub>J</sub> = 125 °C		-	1800	3900	no	
Peak rate of recovery current	dl <sub>(rec)M</sub> /dt	T <sub>J</sub> = 125 °C	-	-	400	A∕µs		
Softness factor per leg		$I_F$ = 50 A, $T_J$ = 25 °C, dI/dt = 400 A/µs, $V_R$ = 200 V		-	0.2	-		
Softness factor per leg s		$I_F = 50 \text{ A}, T_J = 125 \text{ °C}, d$	-	0.22	-			

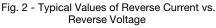
THERMAL AN	THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Maximum junction operating and storage temperature range		T <sub>J</sub> , T <sub>Stg</sub>		- 40 to 150	°C		
Maximum thermal resistance, junction to case per leg		R <sub>thJC</sub>	DC operation	0.16	K/W		
Typical thermal resistance, case to heatsink		R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	rv VV			
Mounting to heatsink			A mounting compound is recommended and the torque should be rechecked after a period of 3 hours	4 to 6	Nine		
torque ± 10 % busbar			to allow the spread of the compound.	4 10 0	Nm		
Approximate weight	+			200	g		
Approximate weight	L			7.1	oz.		
Case style				INT-A	-PAK		



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400

500

600

300

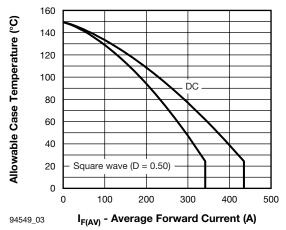


Fig. 3 - Maximum Allowable Case Temperature vs. Average Forward Current

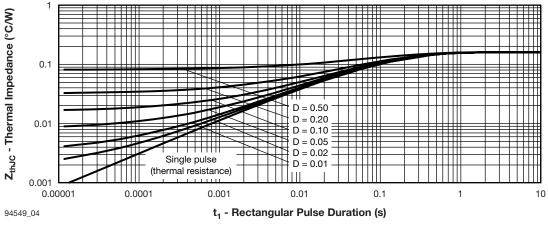


Fig. 4 - Maximum Thermal Impedance ZthJC Characteristics

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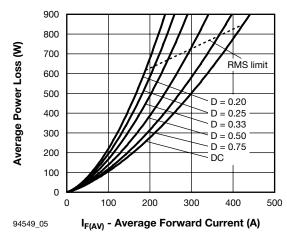


Fig. 5 - Forward Power Loss Characteristics

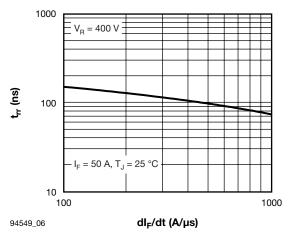
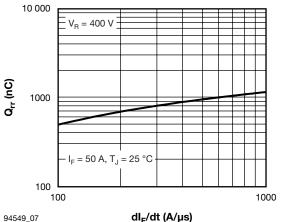
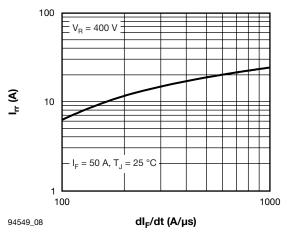


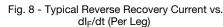
Fig. 6 - Typical Reverse Recovery Time vs. dI<sub>F</sub>/dt (Per Leg)



#### dl<sub>F</sub>/dt (A/µs)

Fig. 7 - Typical Reverse Recovery Charge vs. dl<sub>F</sub>/dt (Per Leg)





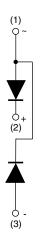


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#### ORDERING INFORMATION TABLE

Device code	vsĸ	D	U	300	1	06	PbF
		2	3	4	<u> </u>	5	6
	1 - 2 -	Circ	dule type cuit confi Double	guratior		ries	
	3 -	U =	Ultrafas	t diode			
	4 -	Cur	rent ratii	ng (300	= 300 A	<b>N</b> )	
	5 -	Volt	age rati	ng (06 =	= 600 V)		
	6 -	PbF	= Lead	(Pb)-fre	e		

#### **CIRCUIT CONFIGURATION**



LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95254			

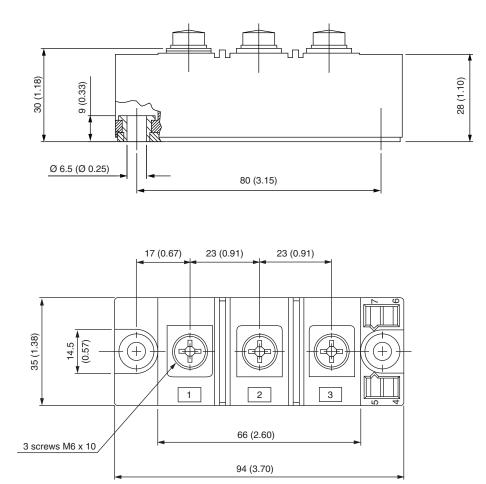


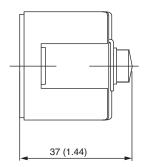
### **Outline Dimensions**

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### **INT-A-PAK DBC**

#### **DIMENSIONS** in millimeters (inches)







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